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# **2SB0873** (2SB873)

#### Silicon PNP epitaxial planar type

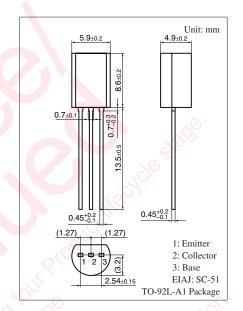
For low-frequency power amplification For DC-DC converter For stroboscope

#### ■ Features

- Low collector-emitter saturation voltage V<sub>CE(sat)</sub>
- Large collector current I<sub>C</sub>

#### ■ Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	$V_{CBO}$	-30	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	-20	V	
Emitter-base voltage (Collector open)	$V_{EBO}$	-7	V	
Collector current	$I_{C}$	-5	A	
Peak collector current	I <sub>CP</sub>	-10	A	
Collector power dissipation	P <sub>C</sub>	1	W	
Junction temperature	T <sub>j</sub>	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	
			20	



#### ■ Electrical Characteristics T<sub>a</sub> = 25°C ± 3°C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	$V_{CEO}$	$I_C = -1 \text{ mA}, I_B = 0$	-20			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = -10 \mu A, I_C = 0$	-7			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = -10 \text{ V}, I_E = 0$			-100	nA
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = -5 \text{ V}, I_C = 0$			-100	nA
Forward current transfer ratio *1, 2	h <sub>FE</sub>	$V_{CE} = -2 \text{ V}, I_{C} = -2 \text{ A}$	90		625	_
Collector-emitter saturation voltage *1	V <sub>CE(sat)</sub>	$I_C = -3 \text{ A}, I_B = -0.1 \text{ A}$			-1	V
Transition frequency	$f_T$	$V_{CB} = -6 \text{ V}, I_E = 50 \text{ mA}, f = 200 \text{ MHz}$		120		MHz
Collector output capacitance (Common-emitter reverse transfer)	C <sub>ob</sub>	$V_{CB} = -20 \text{ V}, I_E = 0, f = 1 \text{ MHz}$			85	pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

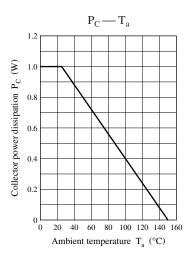
2. \*1: Pulse measurement

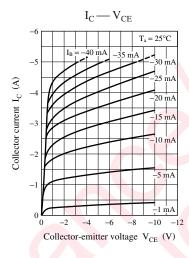
\*2: Rank classification

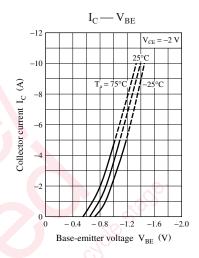
Rank	Р	Q	R
$h_{\mathrm{FE}}$	90 to 135	120 to 205	180 to 625

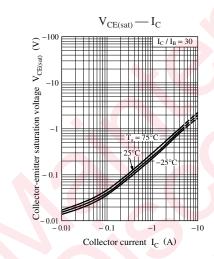
Note) The part number in the parenthesis shows conventional part number.

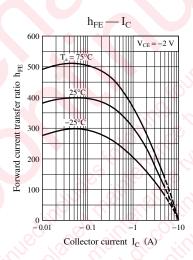
### **Panasonic**

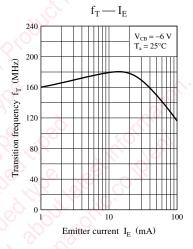


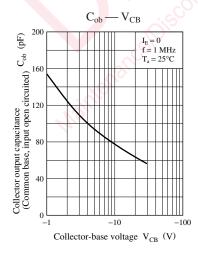


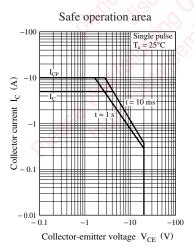












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